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74VCX08

Low Voltage Quad 2-Input AND Gate with 3.6V Tolerant Inputs and Outputs

Features

- 1.2V to 3.6V V_{CC} supply operation
- 3.6V tolerant inputs and outputs
- t_{PD} :
 - 2.8ns max. for 3.0V to 3.6V V_{CC}
- Power-off high impedance inputs and outputs
- Static Drive (I_{OH}/I_{OL})
 - $\pm 24mA$ @ 3.0V V_{CC}
- Uses proprietary Quiet Series™ noise/EMI reduction circuitry
- Latchup performance exceeds 300mA
- ESD performance:
 - Human body model > 2000V
 - Machine model > 250V
- Leadless DQFN package

General Description

The VCX08 contains four 2-input AND gates. This product is designed for low voltage (1.2V to 3.6V) V_{CC} applications with I/O compatibility up to 3.6V.

The VCX08 is fabricated with an advanced CMOS technology to achieve high-speed operation while maintaining low CMOS power dissipation.

Ordering Information

| Order Number | Package Number | Package Description |
|---------------------------|----------------|---|
| 74VCX08M | M14A | 14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow |
| 74VCX08BQX ⁽¹⁾ | MLP14A | 14-Terminal Depopulated Quad Very-Thin Flat Pack No Leads (DQFN), JEDEC MO-241, 2.5 x 3.0mm |
| 74VCX08MTC | MTC14 | 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide |

Note:

1. DQFN package available in Tape and Reel only.

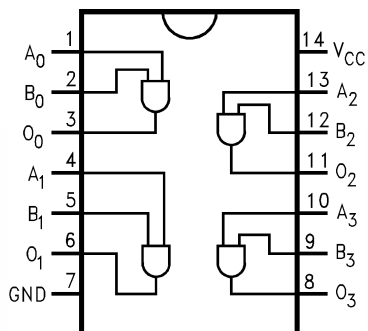
Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.



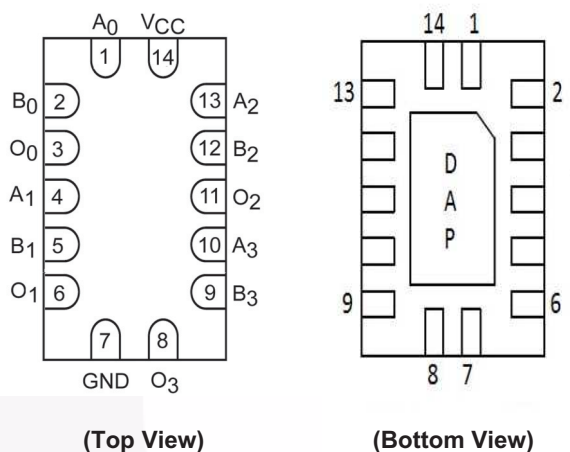
All packages are lead free per JEDEC: J-STD-020B standard.

Connection Diagrams

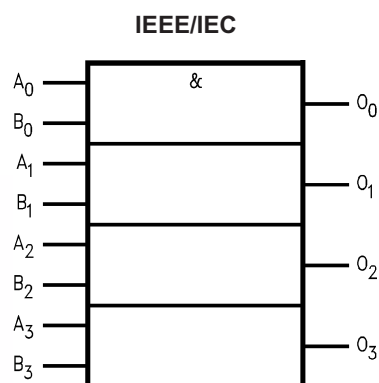
Pin Assignments for SOIC and TSSOP



Pad Assignments for DQFN



Logic Symbol



Pin Description

| Pin Names | Description |
|------------|-------------|
| A_n, B_n | Inputs |
| O_n | Outputs |
| DAP | No Connect |

Note: DAP (Die Attach Pad)

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

| Symbol | Parameter | Rating |
|-------------------|---|------------------------|
| V_{CC} | Supply Voltage | −0.5V to +4.6V |
| V_I | DC Input Voltage | −0.5V to 4.6V |
| V_O | DC Output Voltage HIGH or LOW State ⁽²⁾ | −0.5V to $V_{CC}+0.5V$ |
| | $V_{CC} = 0V$ | −0.5V to +4.6V |
| I_{IK} | DC Input Diode Current, $V_I < 0V$ | −50mA |
| I_{OK} | DC Output Diode Current $V_O < 0V$ | −50mA |
| | $V_O > V_{CC}$ | +50mA |
| I_{OH} / I_{OL} | DC Output Source/Sink Current | +50mA |
| I_{CC} or GND | DC V_{CC} or Ground Current per Supply Pin | ±100mA |
| T_{STG} | Storage Temperature Range | −65°C to +150°C |

Note:

2. I_O Absolute Maximum Rating must be observed.

Recommended Operating Conditions⁽³⁾

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

| Symbol | Parameter | Rating |
|-----------------------|---|----------------|
| V_{CC} | Power Supply Operating | 1.2V to 3.6V |
| V_I | Input Voltage | −0.3V to 3.6V |
| V_O | Output Voltage, HIGH or LOW State | 0V to V_{CC} |
| I_{OH} / I_{OL} | Output Current $V_{CC} = 3.0V$ to 3.6V | ±24mA |
| | $V_{CC} = 2.3V$ to 2.7V | ±18mA |
| | $V_{CC} = 1.65V$ to 2.3V | ±6mA |
| | $V_{CC} = 1.4V$ to 1.6V | ±2mA |
| | $V_{CC} = 1.2V$ | ±100μA |
| T_A | Free Air Operating Temperature | −40°C to +85°C |
| $\Delta t / \Delta V$ | Minimum Input Edge Rate, $V_{IN} = 0.8V$ to 2.0V, $V_{CC} = 3.0V$ | 10ns/V |

Note:

3. Floating or unused inputs must be held HIGH or LOW

DC Electrical Characteristics

| Symbol | Parameter | V _{CC} (V) | Conditions | Min | Max | Units |
|------------------|---------------------------------------|---------------------|---|-----------------------|----------------------|-------|
| V _{IH} | HIGH Level Input Voltage | 2.7–3.6 | | 2.0 | | V |
| | | 2.3–2.7 | | 1.6 | | |
| | | 1.65–2.3 | | $0.65 \times V_{CC}$ | | |
| | | 1.4–1.6 | | $0.65 \times V_{CC}$ | | |
| | | 1.2 | | $0.65 \times V_{CC}$ | | |
| V _{IL} | LOW Level Input Voltage | 2.7–3.6 | | | 0.8 | V |
| | | 2.3–2.7 | | | 0.7 | |
| | | 1.65–2.3 | | | $0.35 \times V_{CC}$ | |
| | | 1.4–1.6 | | | $0.35 \times V_{CC}$ | |
| | | 1.2 | | | $0.05 \times V_{CC}$ | |
| V _{OH} | HIGH Level Output Voltage | 2.7–3.6 | I _{OH} = –100μA | V _{CC} – 0.2 | | V |
| | | 2.7 | I _{OH} = –12mA | 2.2 | | |
| | | 3.0 | I _{OH} = –18mA | 2.4 | | |
| | | 3.0 | I _{OH} = –24mA | 2.2 | | |
| | | 2.3–2.7 | I _{OH} = –100μA | V _{CC} – 0.2 | | |
| | | 2.3 | I _{OH} = –6mA | 2.0 | | |
| | | 2.3 | I _{OH} = –12mA | 1.8 | | |
| | | 2.3 | I _{OH} = –18mA | 1.7 | | |
| | | 1.65–2.3 | I _{OH} = –100μA | V _{CC} – 0.2 | | |
| | | 1.65 | I _{OH} = –6mA | 1.25 | | |
| | | 1.4–1.6 | I _{OH} = –100μA | V _{CC} – 0.2 | | |
| | | 1.4 | I _{OH} = –2mA | 1.05 | | |
| | | 1.2 | I _{OH} = –100μA | V _{CC} – 0.2 | | |
| V _{OL} | LOW Level Output Voltage | 2.7–3.6 | I _{OL} = 100μA | | 0.2 | V |
| | | 2.7 | I _{OL} = 12mA | | 0.4 | |
| | | 3.0 | I _{OL} = 18mA | | 0.4 | |
| | | 3.0 | I _{OL} = 24mA | | 0.55 | |
| | | 2.3–2.7 | I _{OL} = 100μA | | 0.2 | |
| | | 2.3 | I _{OL} = 12mA | | 0.4 | |
| | | 2.3 | I _{OL} = 18mA | | 0.6 | |
| | | 1.65–2.3 | I _{OL} = 100μA | | 0.2 | |
| | | 1.65 | I _{OL} = 6mA | | 0.2 | |
| | | 1.4–1.6 | I _{OL} = 100μA | | 0.2 | |
| | | 1.4 | I _{OL} = 2mA | | 0.35 | |
| | | 1.2 | I _{OL} = 100μA | | 0.05 | |
| I _I | Input Leakage Current | 1.2–3.6 | 0 ≤ V _I ≤ 3.6V | | ±5.0 | μA |
| I _{OFF} | Power-OFF Leakage Current | 0 | 0 ≤ (V _I , V _O) ≤ 3.6V | | 10 | μA |
| I _{CC} | Quiescent Supply Current | 1.2–3.6 | V _I = V _{CC} or GND | | 20 | μA |
| | | | V _{CC} ≤ V _I ≤ 3.6V | | ±20 | |
| ΔI _{CC} | Increase in I _{CC} per Input | 2.7–3.6 | V _{IH} = V _{CC} – 0.6V | | 750 | μA |

AC Electrical Characteristics⁽⁴⁾

| Symbol | Parameter | V _{CC} (V) | Conditions | T _A = –40°C to +85°C | | Units | Figure Number |
|---------------------------------------|--------------------------------------|---------------------|--|---------------------------------|------|-------|------------------|
| | | | | Min. | Max. | | |
| t _{PHL} , t _{PLH} | Propagation Delay | 3.3 ± 0.3 | C _L = 30pF, R _L = 500Ω | 0.6 | 2.8 | ns | Fig. 1 Fig. 2 |
| | | 2.5 ± 0.2 | | 0.8 | 3.7 | | |
| | | 1.8 ± 0.15 | | 1.0 | 7.4 | | |
| | | 1.5 ± 0.1 | C _L = 15pF, R _L = 2kΩ | 1.0 | 14.8 | | Fig. 3 Fig. 4 |
| | | 1.2 | | 1.5 | 37.0 | | |
| t _{OSHL} , t _{OSLH} | Output to Output Skew ⁽⁵⁾ | 3.3 ± 0.3 | C _L = 30pF, R _L = 500Ω | | 0.5 | ns | |
| | | 2.5 ± 0.2 | | | 0.5 | | |
| | | 1.8 ± 0.15 | | | 0.75 | | |
| | | 1.5 ± 0.1 | C _L = 15pF, R _L = 2kΩ | | 1.5 | | |
| | | 1.2 | | | 1.5 | | |

Note:

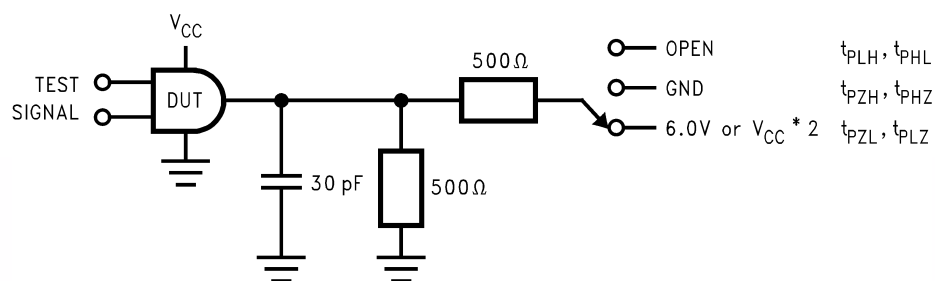
4. For C_L = 50pF, add approximately 300ps to the AC Maximum specification.
5. Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}).

Dynamic Switching Characteristics

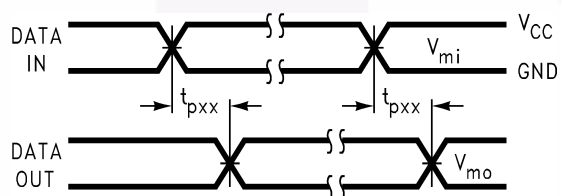
| Symbol | Parameter | V _{CC} (V) | Conditions | T _A = 25°C | Unit |
|------------------|---|---------------------|--|-----------------------|------|
| | | | | Typical | |
| V _{OLP} | Quiet Output Dynamic Peak V _{OL} | 1.8 | C _L = 30pF, V _{IH} = V _{CC} , V _{IL} = 0V | 0.25 | V |
| | | 2.5 | | 0.6 | |
| | | 3.3 | | 0.8 | |
| V _{OLV} | Quiet Output Dynamic Valley V _{OL} | 1.8 | C _L = 30pF, V _{IH} = V _{CC} , V _{IL} = 0V | –0.25 | V |
| | | 2.5 | | –0.6 | |
| | | 3.3 | | –0.8 | |
| V _{OHV} | Quiet Output Dynamic Valley V _{OH} | 1.8 | C _L = 30pF, V _{IH} = V _{CC} , V _{IL} = 0V | 1.5 | V |
| | | 2.5 | | 1.9 | |
| | | 3.3 | | 2.2 | |

Capacitance

| Symbol | Parameter | Conditions | T _A = +25°C | Units |
|------------------|-------------------------------|--|------------------------|-------|
| | | | Typical | |
| C _{IN} | Input Capacitance | V _I = 0V or V _{CC} , V _{CC} = 1.8V, 2.5V or 3.3V | 6.0 | pF |
| C _{OUT} | Output Capacitance | V _I = 0V or V _{CC} , V _{CC} = 1.8V, 2.5V or 3.3V | 7.0 | pF |
| C _{PD} | Power Dissipation Capacitance | V _I = 0V or V _{CC} , f = 10MHz, V _{CC} = 1.8V, 2.5V or 3.3V | 20.0 | pF |

AC Loading and Waveforms (V_{CC} 3.3V \pm 0.3V to 1.8V \pm 0.15V)

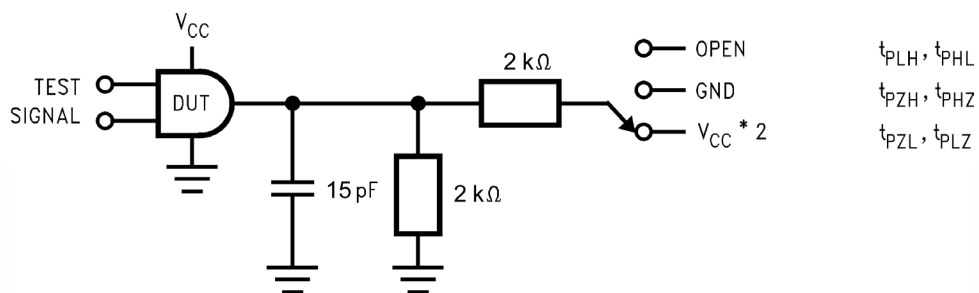
| Test | Switch |
|--------------------|--------|
| t_{PLH}, t_{PHL} | Open |

Figure 1. AC Test Circuit

| Symbol | V_{CC} | | |
|----------|-----------------|-----------------|------------------|
| | 3.3V \pm 0.3V | 2.5V \pm 0.2V | 1.8V \pm 0.15V |
| V_{mi} | 1.5V | $V_{CC} / 2$ | $V_{CC} / 2$ |
| V_{mo} | 1.5V | $V_{CC} / 2$ | $V_{CC} / 2$ |

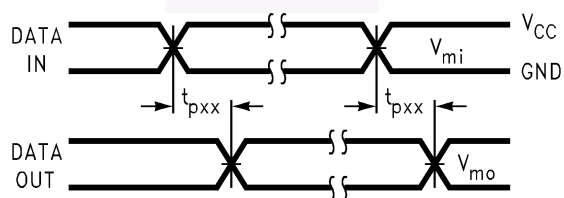
Figure 2. Waveform for Inverting and Non-inverting Functions

AC Loading and Waveforms ($V_{CC} 1.5 \pm 0.1V$ to $1.2V$)



| Test | Switch |
|--------------------|---|
| t_{PLH}, t_{PHL} | Open |
| t_{PZL}, t_{PLZ} | $V_{CC} \times 2$ at $V_{CC} = 1.5V \pm 0.1V$ |
| t_{PZH}, t_{PHZ} | GND |

Figure 3. AC Test Circuit



| Symbol | V_{CC} |
|----------|-----------------|
| | $1.5V \pm 0.1V$ |
| V_{mi} | $V_{CC} / 2$ |
| V_{mo} | $V_{CC} / 2$ |

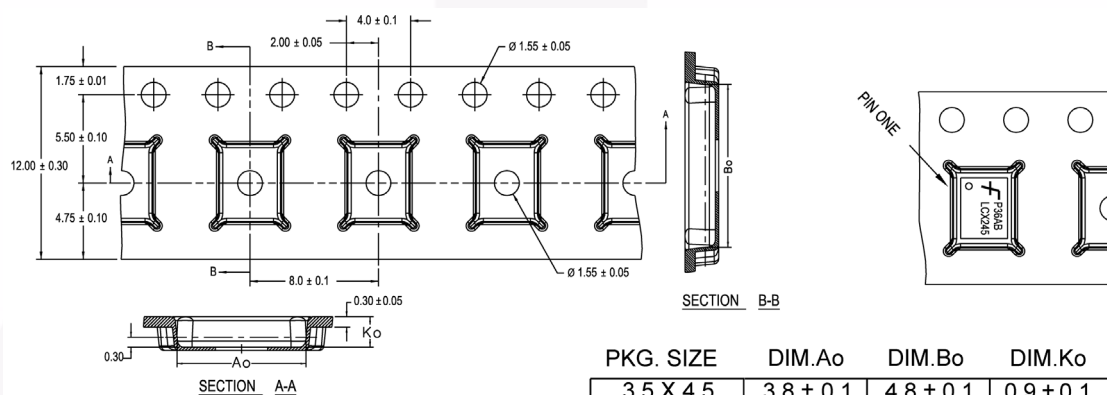
Figure 4. Waveform for Inverting and Non-Inverting Functions

Tape and Reel Specification

Tape Format for DQFN

| Package Designator | Tape Section | Number of Cavities | Cavity Status | Cover Tape Status |
|--------------------|--------------------|--------------------|---------------|-------------------|
| BQX | Leader (Start End) | 125 (Typ.) | Empty | Sealed |
| | Carrier | 3000 | Filled | Sealed |
| | Trailer (Hub End) | 75 (Typ.) | Empty | Sealed |

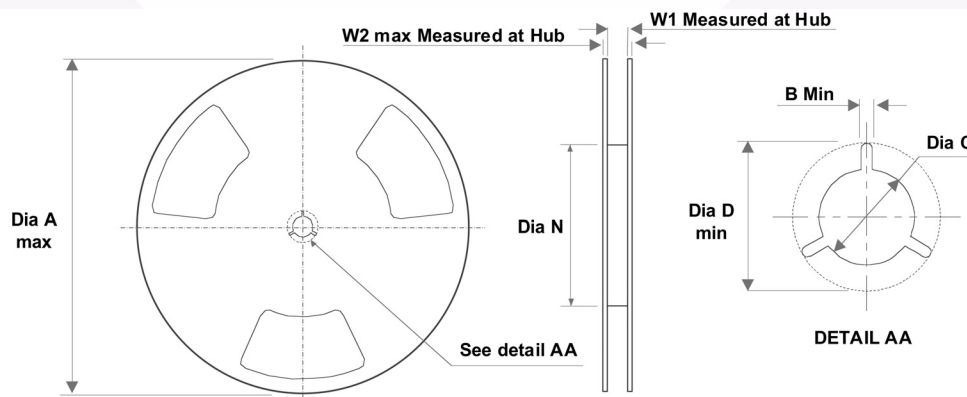
Tape Dimensions inches (millimeters)



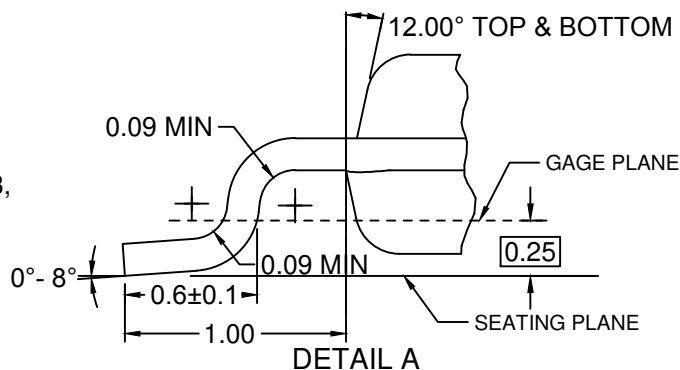
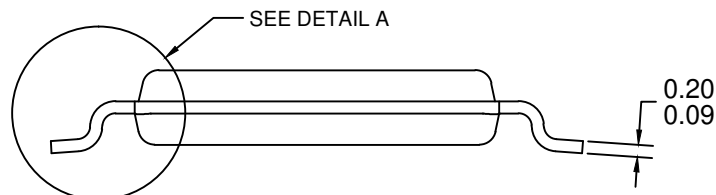
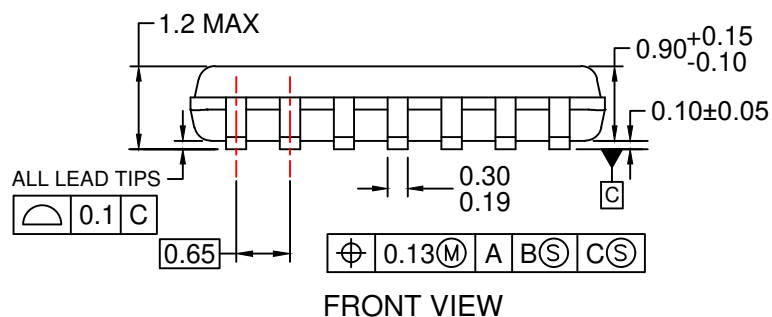
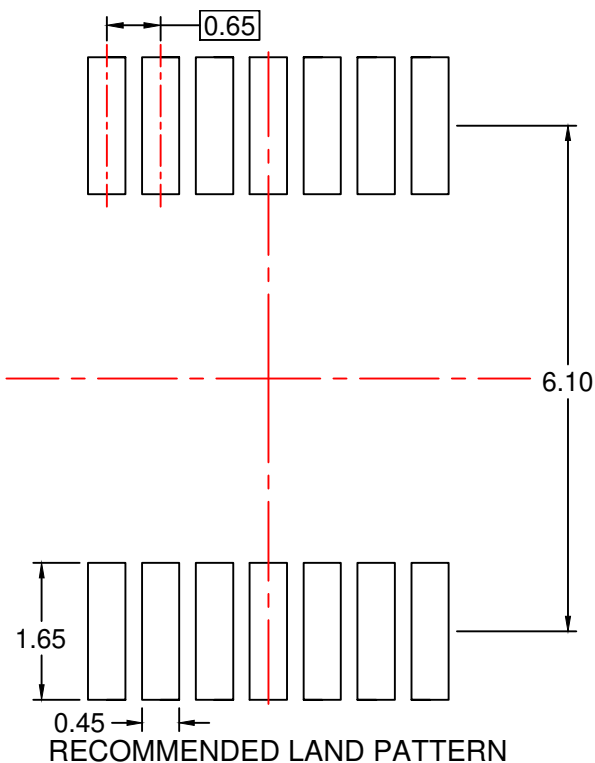
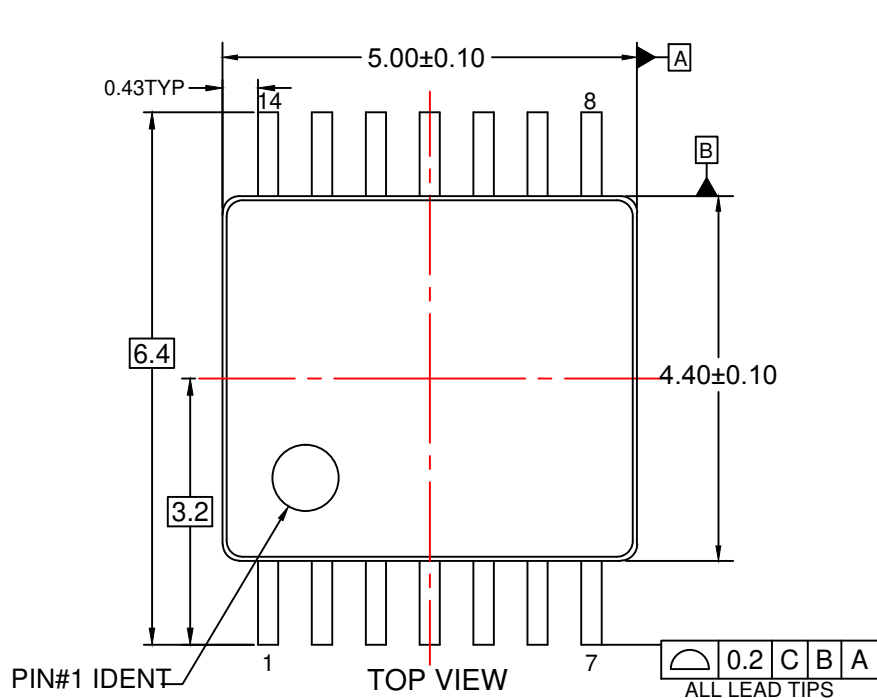
NOTES: unless otherwise specified

1. Cumulative pitch for feeding holes and cavities (chip pockets) not to exceed 0.008[0.20] over 10 pitch span.
2. Smallest allowable bending radius.
3. Thru hole inside cavity is centered within cavity.
4. Tolerance is $\pm 0.002[0.05]$ for these dimensions on all 12mm tapes.
5. Ao and Bo measured on a plane 0.120[0.30] above the bottom of the pocket.
6. Ko measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
7. Pocket position relative to sprocket hole measured as true position of pocket. Not pocket hole.
8. Controlling dimension is millimeter. Dimension in inches rounded.

Reel Dimensions inches (millimeters)



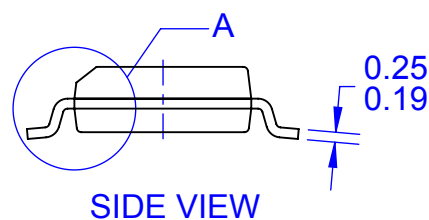
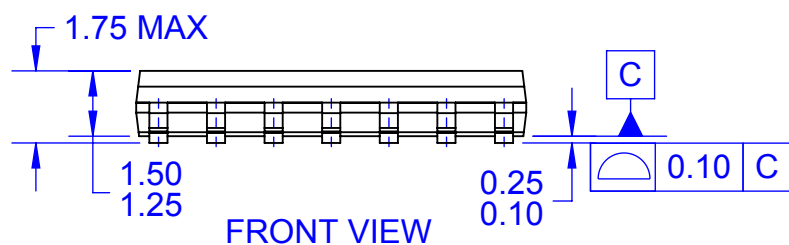
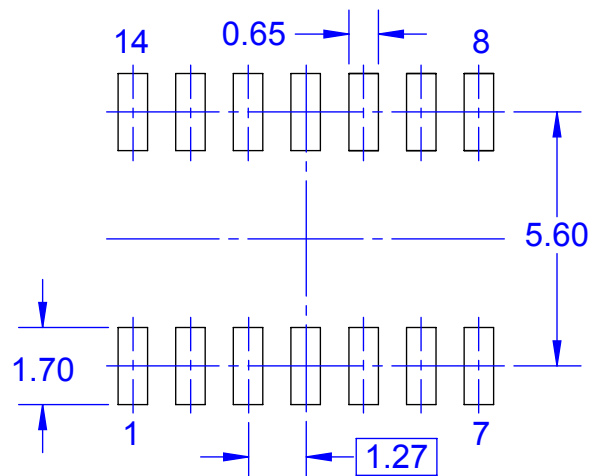
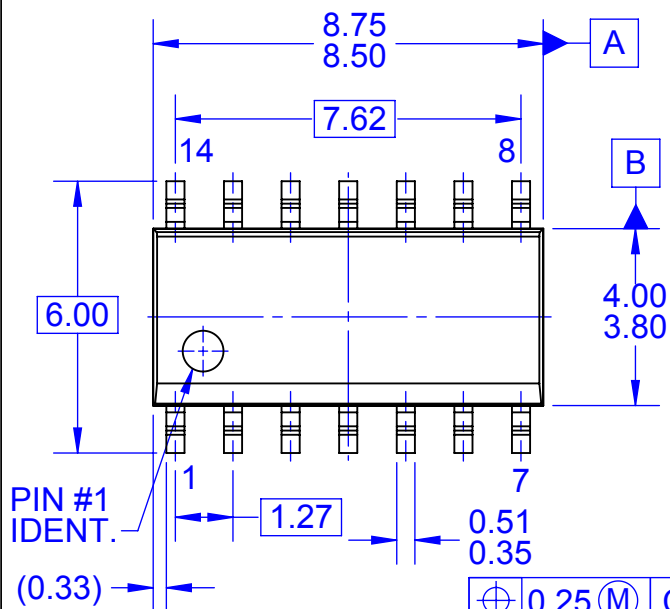
| Tape Size | A | B | C | D | N | W1 | W2 |
|-----------|--------------|--------------|---------------|---------------|---------------|--------------|--------------|
| 12mm | 13.0 (330.0) | 0.059 (1.50) | 0.512 (13.00) | 0.795 (20.20) | 2.165 (55.00) | 0.488 (12.4) | 0.724 (18.4) |



NOTES:

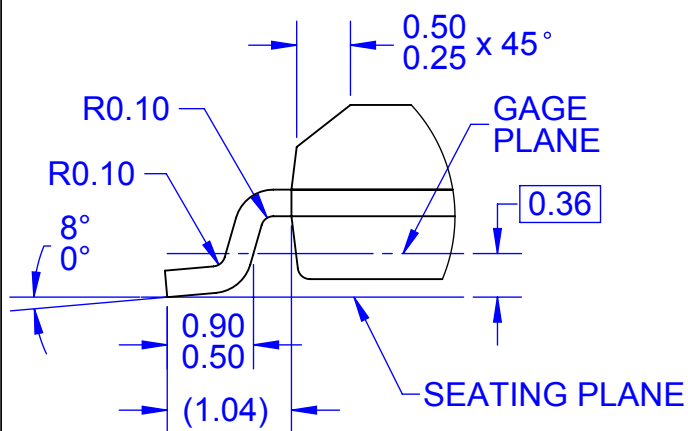
- CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB, REF NOTE 6
- DIMENSIONS ARE IN MILLIMETERS.
- DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
- DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 2009.
- LANDPATTERN STANDARD: SOP65P640X110-14M.
- DRAWING FILE NAME: MKT-MTC14rev7.





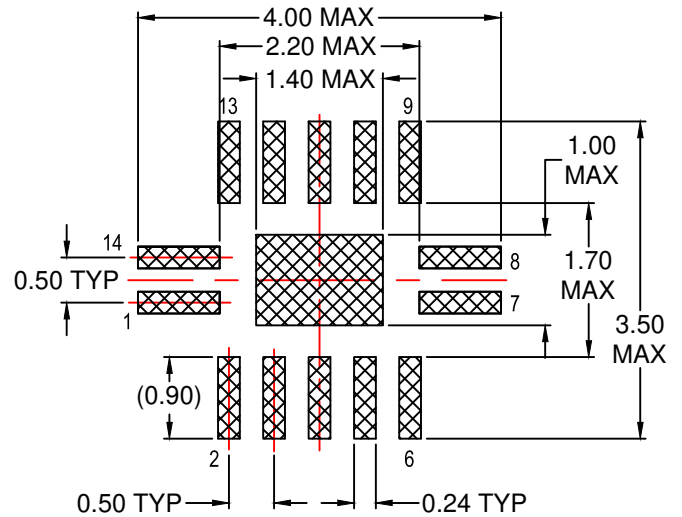
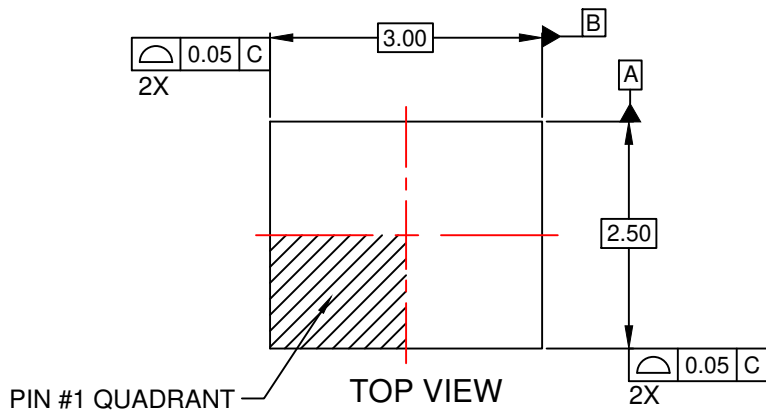
NOTES:

- A. CONFORMS TO JEDEC MS-012, VARIATION AB, ISSUE C
- B. ALL DIMENSIONS ARE IN MILLIMETERS
- C. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS
- D. LAND PATTERN STANDARD: SOIC127P600X145-14M
- E. CONFORMS TO ASME Y14.5M, 2009
- D. DRAWING FILENAME: MKT-M14Arev14

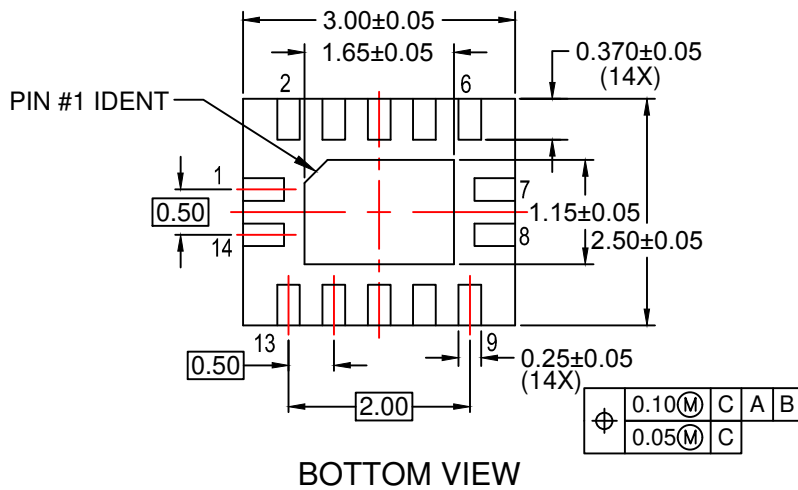
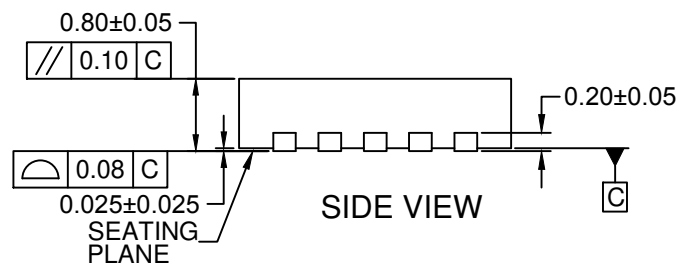


DETAIL A
SCALE 16 : 1





RECOMMENDED LAND PATTERN



NOTES:

- CONFORMS TO JEDEC REGISTRATION MO-241, VARIATION AA
- DIMENSIONS ARE IN MILLIMETERS.
- DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
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